



Is Now Part of



**ON Semiconductor®**

To learn more about ON Semiconductor, please visit our website at  
[www.onsemi.com](http://www.onsemi.com)

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (\_), the underscore (\_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (\_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at [www.onsemi.com](http://www.onsemi.com). Please email any questions regarding the system integration to [Fairchild\\_questions@onsemi.com](mailto:Fairchild_questions@onsemi.com).

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.



August 2016

# MCT6, MCT61, MCT62 8-Pin Dual Channel Phototransistor Optocouplers

## Features

- Two Isolated Channels Per Package
- Safety and Regulatory Approvals:
  - UL1577, 5,000 VAC<sub>RMS</sub> for 1 Minute
  - DIN-EN/IEC60747-5-5, 890 V Peak Working Insulation Voltage

## Applications

- AC line/digital logic – isolate high voltage transients
- Digital logic/digital logic – eliminate spurious grounds
- Digital logic/AC triac control – isolate high voltage transients
- Twisted pair line receiver – eliminate ground loop feedthrough
- Telephone/telegraph line receiver – isolate high voltage transients
- High frequency power supply feedback control – maintain floating grounds and transients
- Relay contact monitor – isolate floating grounds and transients
- Power supply monitor – isolate transients

## Description

The general purpose optocouplers, MCT6, MCT61, and MCT62, have two isolated channels in a standard plastic 8-pin dual-in-line (DIP) package for density applications. Each channel consists of a gallium arsenide infrared emitting diode driving a NPN silicon planar phototransistor. For four channel applications, two packages fit into a standard 16-pin DIP socket.

## Functional Schematic

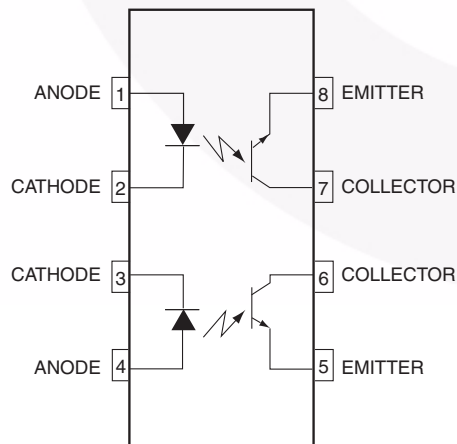


Figure 1. Schematic

## Package Outlines

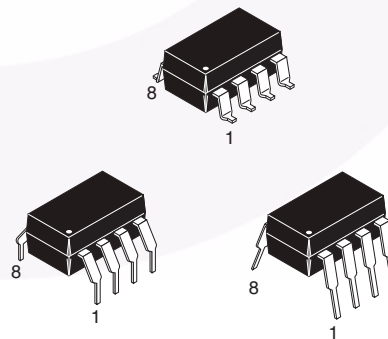


Figure 2. Package Outlines

MCT6, MCT61, MCT62 8-Pin Dual Channel Phototransistor Optocouplers

## Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter		Characteristics
Installation Classifications per DIN VDE 0110/1.89 Table 1, For Rated Mains Voltage	< 150 V <sub>RMS</sub>	I–IV
	< 300 V <sub>RMS</sub>	I–IV
Climatic Classification		55/115/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
V <sub>PR</sub>	Input-to-Output Test Voltage, Method A, V <sub>IORM</sub> × 1.6 = V <sub>PR</sub> , Type and Sample Test with t <sub>m</sub> = 10 s, Partial Discharge < 5 pC	1424	V <sub>peak</sub>
	Input-to-Output Test Voltage, Method B, V <sub>IORM</sub> × 1.875 = V <sub>PR</sub> , 100% Production Test with t <sub>m</sub> = 1 s, Partial Discharge < 5 pC	1668	V <sub>peak</sub>
V <sub>IORM</sub>	Maximum Working Insulation Voltage	890	V <sub>peak</sub>
V <sub>IOTM</sub>	Highest Allowable Over-Voltage	8000	V <sub>peak</sub>
	External Creepage	≥ 7	mm
	External Clearance	≥ 7	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.4	mm
T <sub>S</sub>	Case Temperature <sup>(1)</sup>	175	°C
I <sub>S,INPUT</sub>	Input Current <sup>(1)</sup>	60	mA
P <sub>S,OUTPUT</sub>	Output Power <sup>(1)</sup>	150	mW
R <sub>IO</sub>	Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V <sup>(1)</sup>	> 10 <sup>9</sup>	Ω

### Note:

1. Safety limit values – maximum values allowed in the event of a failure.

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Value	Unit
$T_{STG}$	Storage Temperature	-55 to +150	$^\circ\text{C}$
$T_{OPR}$	Operating Temperature	-55 to +100	$^\circ\text{C}$
$T_J$	Junction Temperature	-55 to +125	$^\circ\text{C}$
$T_{SOL}$	Lead Solder Temperature	260 for 10 seconds	$^\circ\text{C}$
$P_D$	Total Device Power Dissipation @ $T_A = 25^\circ\text{C}$	400	mW
	Derate Above $25^\circ\text{C}$	5.33	mW/ $^\circ\text{C}$
<b>EMITTER (Each channel)</b>			
$I_F$	DC / Average Forward Input Current	60	mA
$I_F(pk)$	Forward Current - Peak (PW = 1 $\mu\text{s}$ , 300pps)	3	A
$V_R$	Reverse Input Voltage	3	V
$P_{D(EMITTER)}$	Total Power Dissipation @ $T_A = 25^\circ\text{C}$	100	mW
	Derate Above $25^\circ\text{C}$	1.3	mW/ $^\circ\text{C}$
<b>DETECTOR</b>			
$I_C$	Continuous Collector Current	30	mA
$P_{D(DETECTOR)}$	Total Power Dissipation @ $T_A = 25^\circ\text{C}$	150	mW
	Derate Above $25^\circ\text{C}$	2.0	mW/ $^\circ\text{C}$

## Electrical Characteristics

$T_A = 25^\circ\text{C}$  unless otherwise specified.

### Individual Component Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>EMITTER</b>						
$V_F$	Input Forward Voltage	$I_F = 20\text{ mA}$		1.2	1.5	V
$V_R$	Reverse Voltage	$I_R = 10\ \mu\text{A}$	3	25		V
$I_R$	Reverse Leakage Current	$V_R = 5\text{ V}$		0.001	10	$\mu\text{A}$
$C_J$	Junction Capacitance	$V_F = 0\text{ V}, f = 1\text{ MHz}$		50		pF
<b>DETECTOR</b>						
$BV_{CEO}$	Collector-to-Emitter Breakdown Voltage	$I_C = 1.0\text{ mA}, I_F = 0$	30	85		V
$BV_{ECO}$	Emitter-to-Collector Breakdown Voltage	$I_E = 100\ \mu\text{A}, I_F = 0$	6	13		V
$I_{CEO}$	Collector-to-Emitter Dark Current	$V_{CE} = 10\text{ V}, I_F = 0$		5	100	nA
$C_{CE}$	Capacitance	$V_{CE} = 0\text{ V}, f = 1\text{ MHz}$		8		pF

### Transfer Characteristics

Symbol	Parameter	Device	Test Conditions	Min.	Typ.	Max.	Unit
<b>DC CHARACTERISTICS</b>							
CTR	Current Transfer Ratio, Collector-to-Emitter	MCT6	$I_F = 10\text{ mA}, V_{CE} = 10\text{ V}$	20			%
		MCT61	$I_F = 5\text{ mA}, V_{CE} = 5\text{ V}$	50			
		MCT62		100			
$V_{CE(SAT)}$	Saturation Voltage, Collector-to-Emitter	ALL	$I_F = 16\text{ mA}, I_C = 2\text{ mA}$		0.15	0.4	V

### AC CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Non-Saturated</b>						
$T_{ON}$	Turn-On Time	$R_L = 100\ \Omega, I_C = 2\text{ mA}, V_{CC} = 10\text{ V}$		3.0		$\mu\text{s}$
$T_{OFF}$	Turn-Off Time			3.0		$\mu\text{s}$
$T_R$	Rise Time			2.4		$\mu\text{s}$
$T_F$	Fall Time			2.4		$\mu\text{s}$
<b>Saturated</b>						
$T_{ON}$	Turn-On Time	$I_F = 16\text{ mA}, R_L = 1.9\text{ k}\Omega, V_{CE} = 5\text{ V}$		2.4		$\mu\text{s}$
$T_{OFF}$	Turn-Off Time			25.0		$\mu\text{s}$

### Isolation Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{ISO}$	Input-Output Isolation Voltage	$I_{I-O} \leq 10\ \mu\text{A}, t = 1\text{ Minute}$	5,000			$V_{AC_{RMS}}$
$C_{ISO}$	Isolation Capacitance	$f = 1\text{ MHz}$		0.5		pF
$R_{ISO}$	Isolation Resistance	$V_{I-O} = 500\text{ VDC}$	$10^{11}$			$\Omega$

## Typical Performance Curves

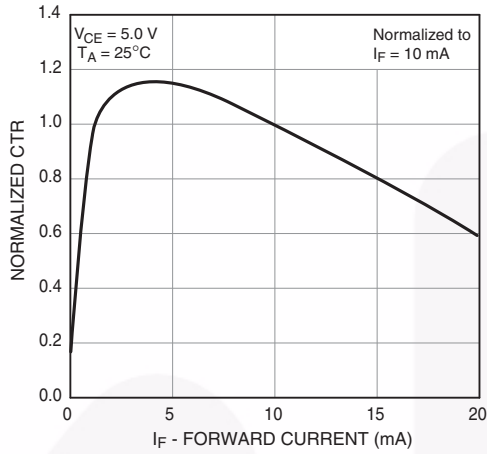


Fig. 3 Normalized CTR vs. Forward Current

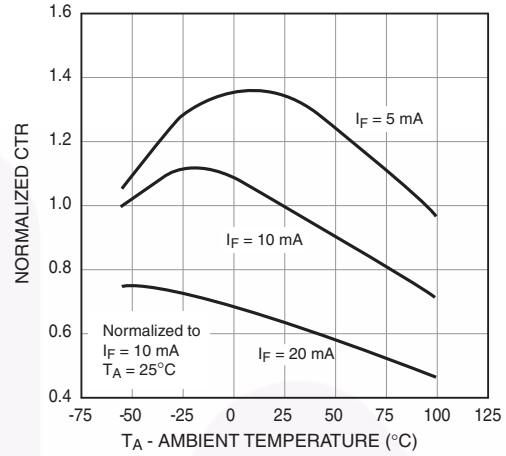


Fig. 4 Normalized CTR vs. Ambient Temperature

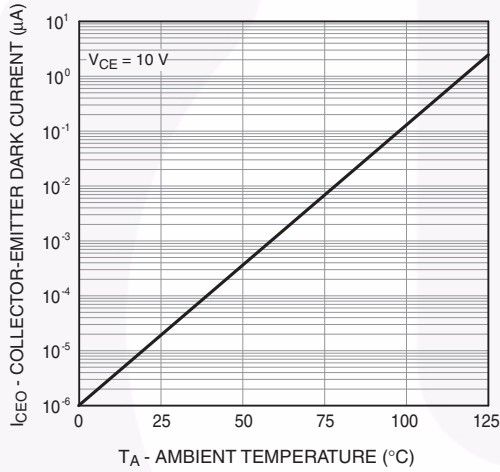


Fig. 5 Dark Current vs. Ambient Temperature

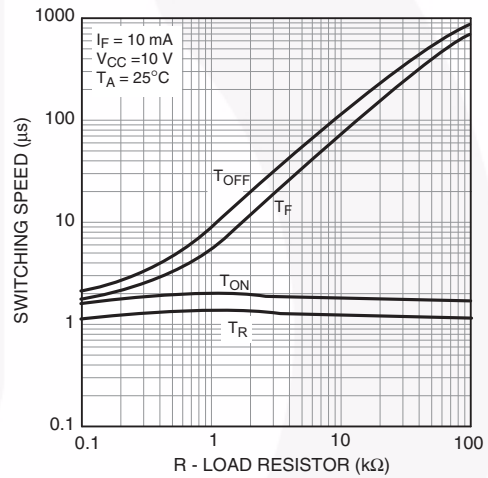


Fig. 6 Switching Speed vs. Load Resistor

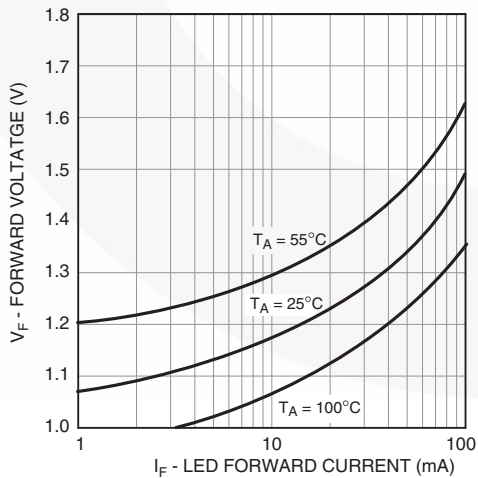


Fig. 7 LED Forward Voltage vs. Forward Current

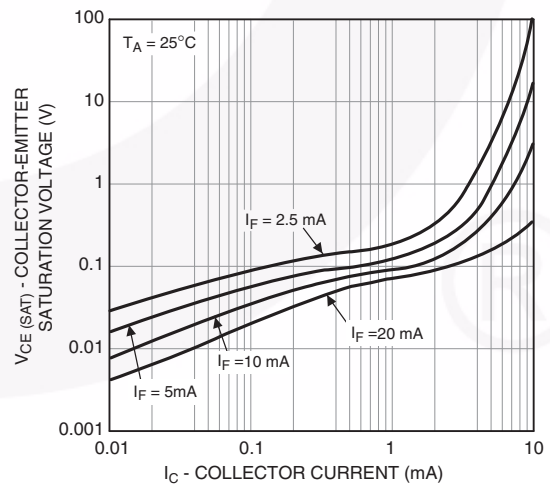


Fig. 8 Collector-Emmitter Saturation Voltage vs. Collector Current

### Switching Time Test Circuit and Waveforms

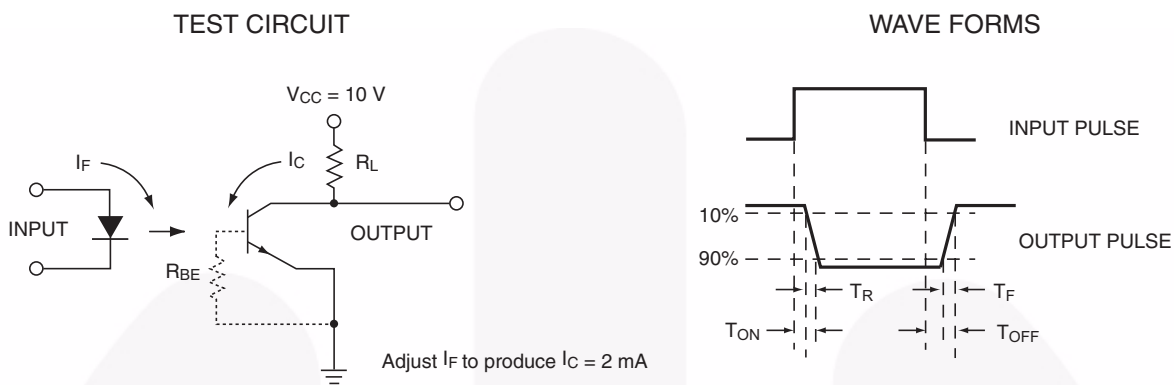
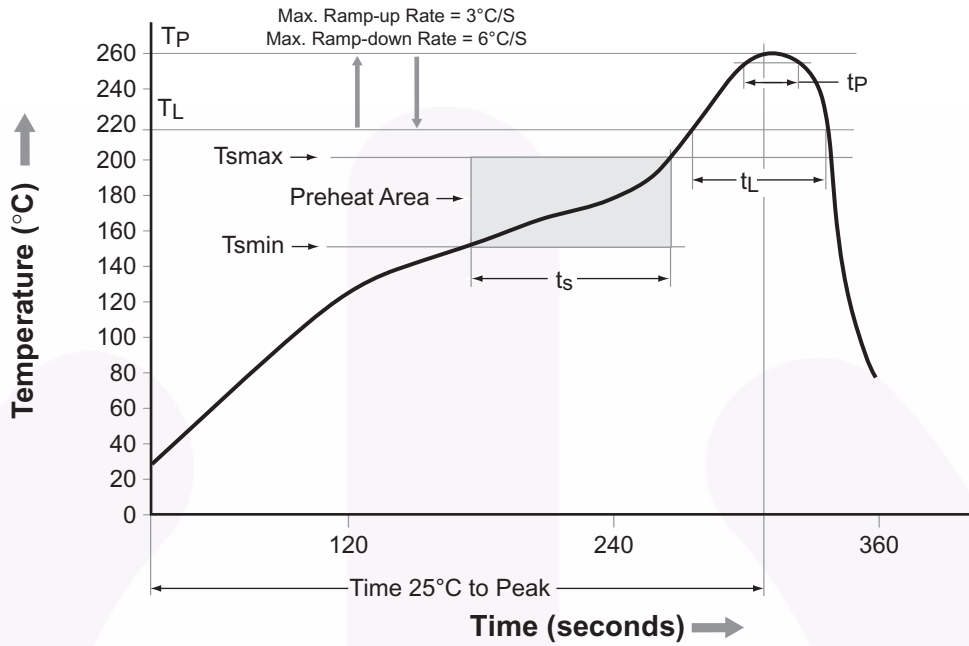


Figure 9. Switching Time Test Circuit and Waveforms



**Reflow Profile**



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmmin)	150°C
Temperature Max. (Tsmmax)	200°C
Time (ts) from (Tsmmin to Tsmmax)	60–120 seconds
Ramp-up Rate (tL to tp)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60–150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (tp) within 5°C of 260°C	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.





## Ordering Information

Part Number	Package	Packing Method
MCT6	DIP 8-Pin	Tube (50 units per tube)
MCT6S	SMT 8-Pin (Lead Bend)	Tube (50 units per tube)
MCT6SD	SMT 8-Pin	Tape and Reel (1,000 units per reel)
MCT6300	DIN EN/IEC 60747-5-5 Option	Tube (50 units per tube)
MCT63S	SMT 8-Pin (Lead Bend); DIN EN/IEC 60747-5-5 Option	Tube (50 units per tube)
MCT63SD	SMT 8-Pin; DIN EN/IEC 60747-5-5 Option	Tape and Reel (1,000 units per reel)
MCT6300W	0.4" Lead Spacing; DIN EN/IEC 60747-5-5 Option	Tube (50 units per tube)

### Note

- The product orderable part number system listed in this table also applies to the MCT61 and MCT62.

## Marking Information

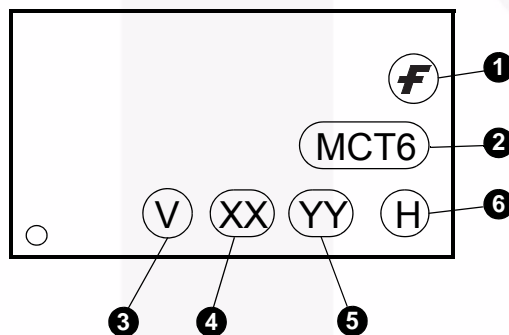
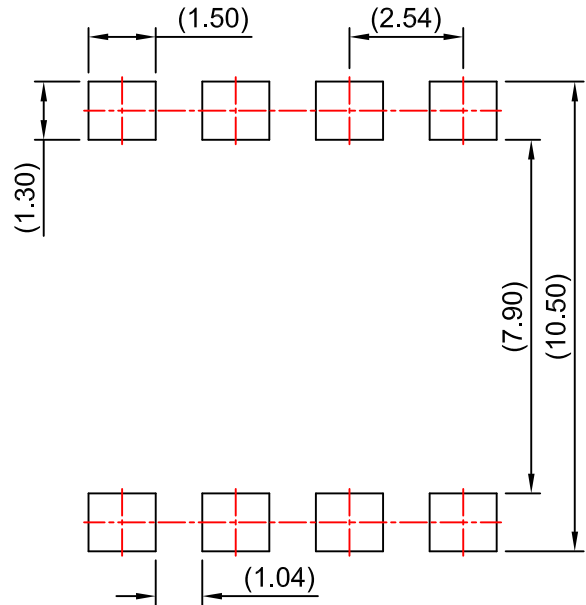
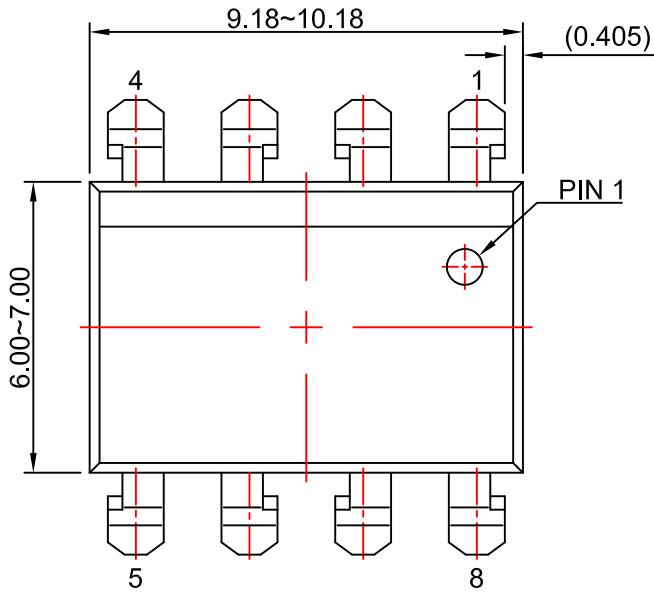


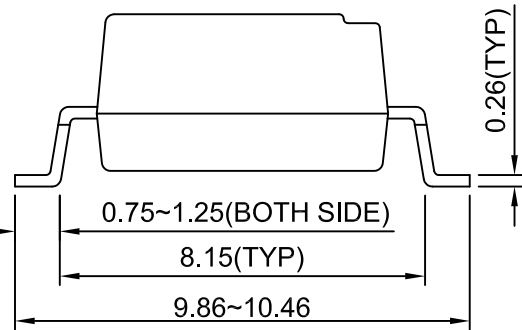
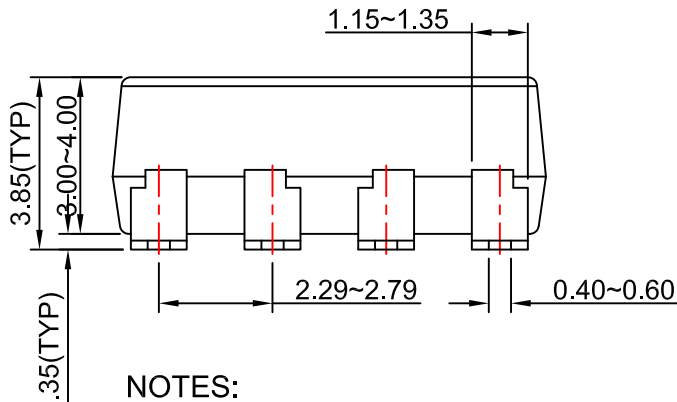
Figure 10. Top Mark

Table 1. Top Mark Definitions

1	Fairchild Logo
2	Device Number
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)
4	Two-Digit Year Code, e.g., "16"
5	Digit Work Week, Ranging from "01" to "53"
6	Assembly Package Code



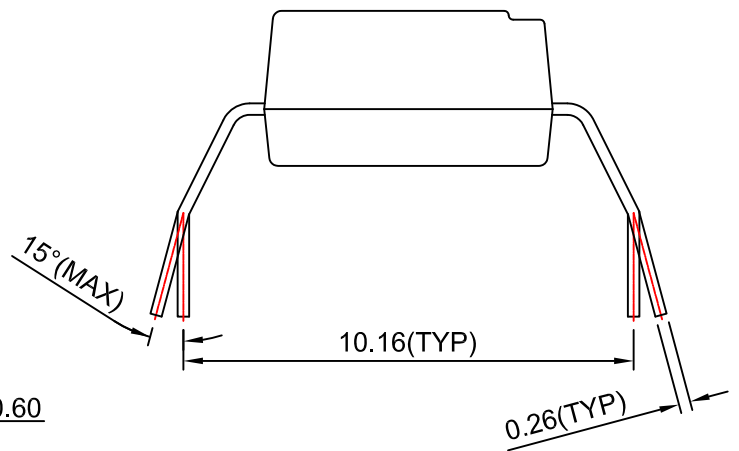
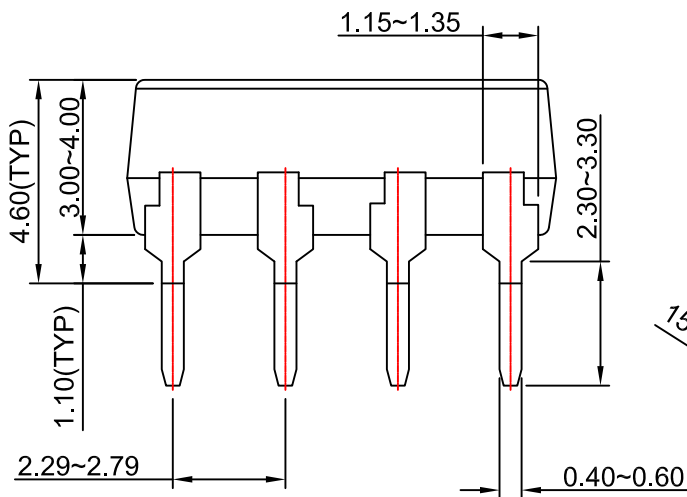
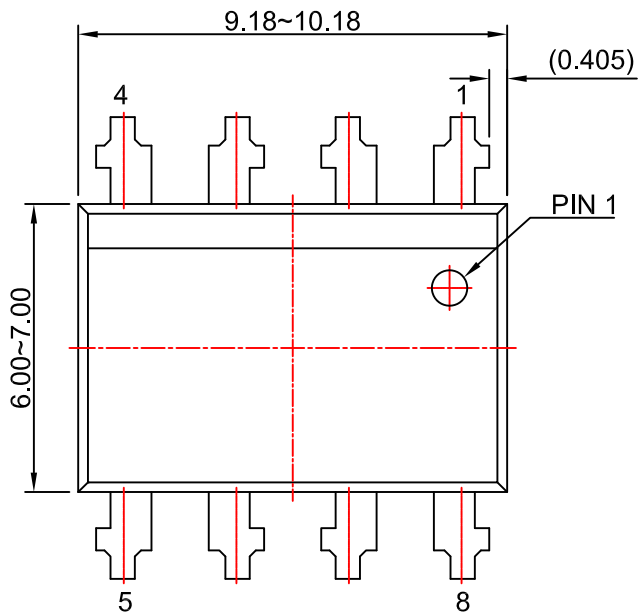
LAND PATTERN RECOMMENDATION



NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N08Krev2.





NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N08Jrev2.





- NOTES:  
 A) NO STANDARD APPLIES TO THIS PACKAGE  
 B) ALL DIMENSIONS ARE IN MILLIMETERS.  
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION  
 D) DRAWING FILENAME AND REVISION: MKT-N08GREV7



ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## PUBLICATION ORDERING INFORMATION

### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor  
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA  
**Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
**Email:** [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

**N. American Technical Support:** 800-282-9855 Toll Free  
USA/Canada  
**Europe, Middle East and Africa Technical Support:**  
Phone: 421 33 790 2910  
**Japan Customer Focus Center**  
Phone: 81-3-5817-1050

**ON Semiconductor Website:** [www.onsemi.com](http://www.onsemi.com)  
**Order Literature:** <http://www.onsemi.com/orderlit>  
For additional information, please contact your local  
Sales Representative